



TECHNOLOGY & MARKET ANALYST | ADVANCED PACKAGING & MANUFACTURING

With offices in France, Germany, Japan, Greater China and the U.S.A, Yole Développement (Yole) the « More than Moore » company, provides market research, technology analysis, strategic consulting, media services and financial services to a worldwide customer base.

Covering emerging and disruptive silicon and micro manufacturing markets, the group supports companies, investors and R&D organizations by delivering comprehensive analysis that helps them understand the markets and technology trends critical to their business.

JOB DESCRIPTION

Our company proposes an immediate opening for a Market and Technology Analyst to help us further develop our Advanced Packaging activities by performing market, technology, and strategic analysis.

You will work in close collaboration within the Advanced Packaging & Semiconductor Manufacturing team as well as take part in the projects of the different Business Units (Power / Compounds, MEMS & Sensors, MedTech, LED / Display).

Regular business trips (Europe, USA, Asia) are expected

YOUR RESPONSABILITIES

As an Advanced Packaging Analyst Expert, you will be responsible to :

- Execute technical, marketing, and strategic analysis
- Oversee technology and industry insights from Advanced Packaging and Semiconductor Manufacturing market trends, from devices to package type (3D, fan-out, flip chip, embedded die...)
- Understand the impact of the emergence of new or improved technologies in various applications
- Execute projects within a given timeframe and budget.
- Participate in the establishment and structuration of commercial offers
- Create and manage long-term relationships with customers
- Collect information and promote our activities in conferences and dedicated trade-shows
- Give presentations at international conferences and workshops.

EDUCATION / EXPERIENCE

- Experience (3-5 years) in the semiconductor and possibly in the advanced packaging field
- Good knowledge of the Advanced Packaging technologies : 3D, System In Package, flip chip, fan out, wafer-level-packaging as well as advanced substrate
- University Degree (Master, Engineer, PhD) in a semiconductor-related field is mandatory (Materials Science, Microelectronics, Electronics or equivalent.)
- Strong interest in product market entry / applications (marketing, strategic planning, etc.).
- Required English level: minimum CECR - C1 / TOEIC 900.

Please send your latest CV & cover letter to recruiting@yole.fr

